

1N4148WS-BL-AH

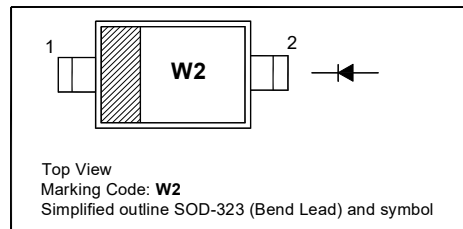
Silicon Epitaxial Planar Switching Diode

Features

- AEC-Q101 Qualified
- SOD-323(Bend Lead) package
- Fast switching
- These diodes are also available in other case style including the DO-35 case with the type designation 1N4148, the MiniMELF case with the type designation LL4148 and the MicroMELF case with the type designation MCL4148.
- Halogen and Antimony Free(HAF), RoHS compliant

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

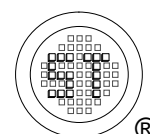


Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V_{RM}	100	V
Reverse Voltage	V_R	75	V
Average Rectified Forward Current	$I_{F(AV)}$	150	mA
Surge Forward Current at $t < 1 \mu\text{s}$ at $t < 1 \text{ s}$	I_{FSM}	2 1	A
Power Dissipation	P_{tot}	200	mW
Thermal Resistance from Junction to Ambient Air	$R_{\theta JA}$	625	$^\circ\text{C/W}$
Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 65 to + 150	$^\circ\text{C}$

Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at $I_R = 1 \mu\text{A}$	$V_{(BR)R}$	75	-	V
Forward Voltage at $I_F = 1 \text{ mA}$ at $I_F = 10 \text{ mA}$ at $I_F = 50 \text{ mA}$ at $I_F = 150 \text{ mA}$	V_F	- - - -	0.715 0.855 1 1.25	V
Peak Reverse Current at $V_R = 75 \text{ V}$ at $V_R = 20 \text{ V}$ at $V_R = 75 \text{ V}$, $T_j = 150^\circ\text{C}$ at $V_R = 25 \text{ V}$, $T_j = 150^\circ\text{C}$	I_R	- - - -	1 25 50 30	μA nA μA μA
Total Capacitance at $V_R = 0 \text{ V}$, $f = 1 \text{ MHz}$	C_T	-	2	pF
Reverse Recovery Time at $I_{rr} = 0.1 \times I_R$, $I_F = 10 \text{ mA}$, $V_R = 6 \text{ V}$, $R_L = 100 \Omega$	t_{rr}	-	4	ns



Electrical Characteristics Curves

Fig 1. Power Dissipation vs Ambient Temperature

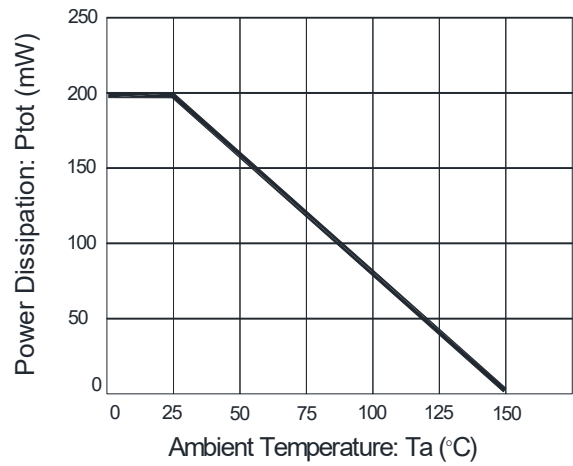


Fig 2. Total Capacitance vs. Reverse Voltage

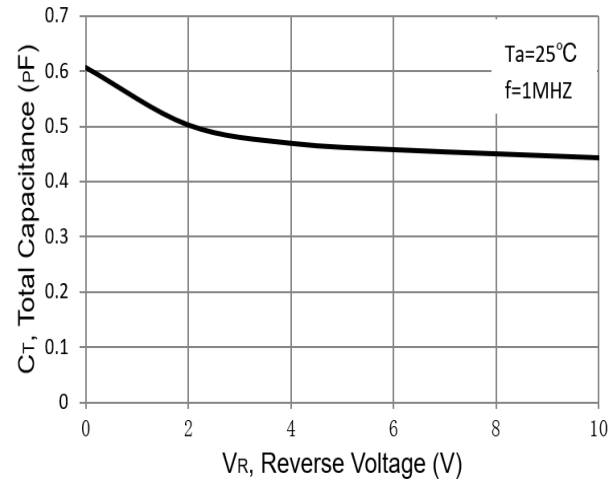


Fig 3. Reverse Current vs. Reverse Voltage

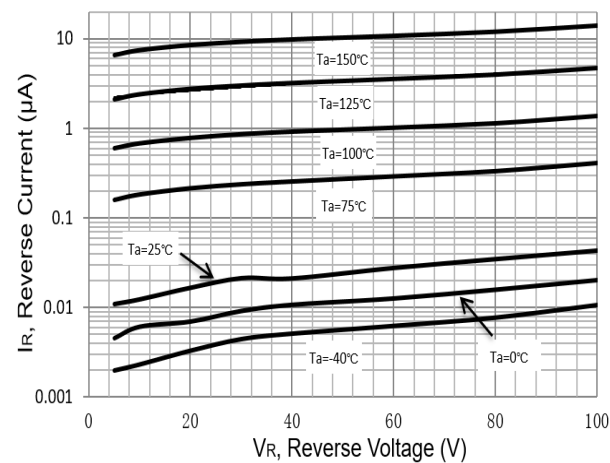
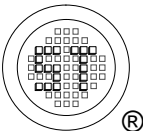
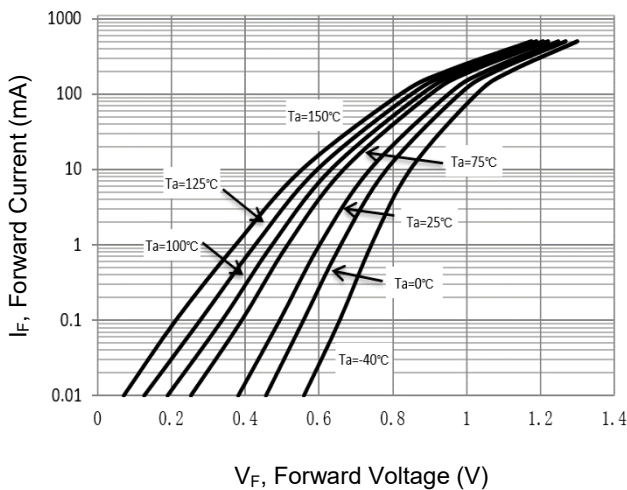


Fig 4. Forward Characteristics

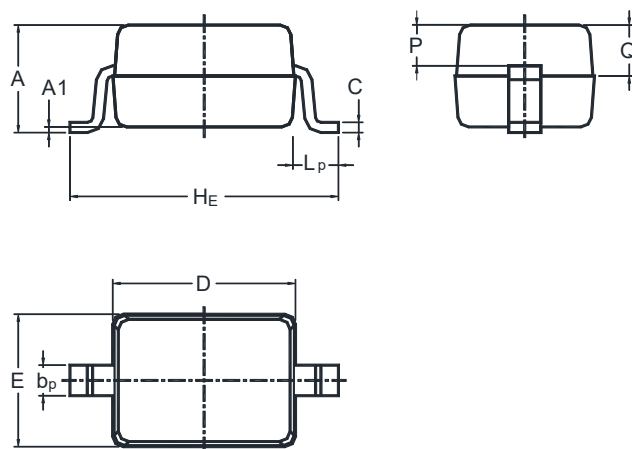


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PACKAGE OUTLINE

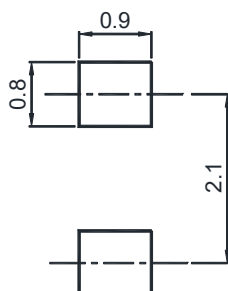
Plastic surface mounted package; 2 leads

SOD-323(Bend Lead)



UNIT	A	A ₁	b _P	C	D	E	H _E	L _P	Q	P
mm	1.1 0.8	0.1 0	0.4 0.25	0.18 0.09	1.8 1.6	1.35 1.15	2.8 2.3	0.5 0.1	0.5 0.3	0.4 0.3

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOD-323BL	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

" III " = Cathode line

" • " = HAF (Halogen and Antimony Free)

" W2 " = Part No.

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